



# 74AHC244Q

## Octal Buffer/Line Driver with 3-State Outputs

### GENERAL DESCRIPTION

The 74AHC244Q is an octal buffer/line driver with 3-state outputs. The device can be used as two 4-bit buffers or one 8-bit buffer. The  $1\overline{OE}$  and  $2\overline{OE}$  are two output enable inputs, and each controls four of the 3-state outputs. When  $n\overline{OE}$  is set high, the outputs are in high-impedance state. When  $n\overline{OE}$  is set low, data transmits from the  $nAn$  inputs to the  $nYn$  outputs.

The over-voltage tolerant inputs can come up to 5.5V. With this function, this device can be used as a translator in mixed voltage environment.

This device is AEC-Q100 qualified (Automotive Electronics Council Standard Q100 Grade 1) and the use of this device is suitable for automotive applications.

### FEATURES

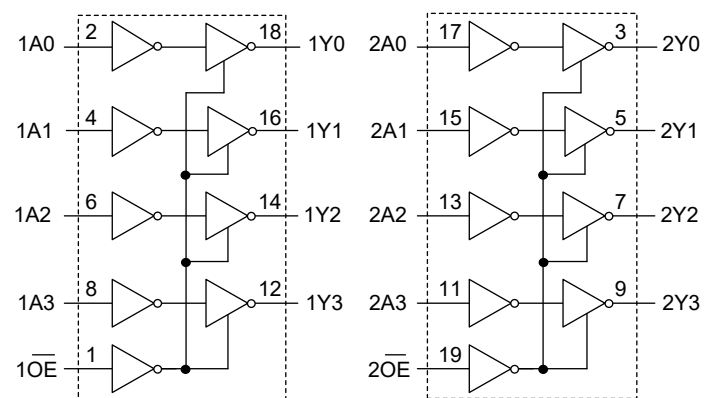
- **AEC-Q100 Qualified for Automotive Applications**  
Device Temperature Grade 1  
 $T_A = -40^\circ\text{C}$  to  $+125^\circ\text{C}$
- **Wide Supply Voltage Range: 2.0V to 5.5V**
- **All Inputs with Schmitt-Trigger Action**
- **Input Level: CMOS Level**
- **CMOS Low Power Dissipation**
- **Inputs are Over-Voltage Tolerant**
- **$-40^\circ\text{C}$  to  $+125^\circ\text{C}$  Operating Temperature Range**
- **Available in a Green TSSOP-20 Package**

### FUNCTION TABLE

CONTROL INPUT	INPUT	OUTPUT
$n\overline{OE}$	$nAn$	$nYn$
L	L	L
L	H	H
H	X	Z

H = High Voltage Level  
L = Low Voltage Level  
Z = High-Impedance State  
X = Don't Care

### LOGIC DIAGRAM



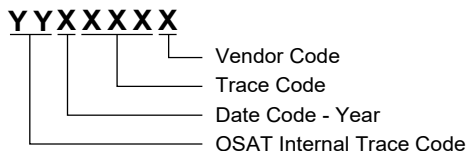
## 74AHC244Q

### PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
74AHC244Q	TSSOP-20	-40°C to +125°C	74AHC244QTS20G/TR	00ZTS20 YYXXXXX	Tape and Reel, 4000

### MARKING INFORMATION

NOTE: YYXXXXX = Date Code, Trace Code and Vendor Code.



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

### ABSOLUTE MAXIMUM RATINGS <sup>(1)</sup>

Supply Voltage, $V_{CC}$ .....	-0.5V to 7.0V
Input Voltage, $V_I$ <sup>(2)</sup> .....	-0.5V to 7.0V
Output Voltage, $V_O$ <sup>(2)</sup> .....	-0.5V to MIN(7.0V, $V_{CC} + 0.5V$ )
Input Clamp Current, $I_{IK}$ ( $V_I < -0.5V$ ).....	-20mA
Output Clamp Current, $I_{OK}$ ( $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ ).....	$\pm 20mA$
Output Current, $I_O$ ( $V_O = -0.5V$ to $V_{CC} + 0.5V$ ).....	$\pm 25mA$
Supply Current, $I_{CC}$ .....	75mA
Ground Current, $I_{GND}$ .....	-75mA
Junction Temperature <sup>(3)</sup> .....	+150°C
Storage Temperature Range.....	-65°C to +150°C
Lead Temperature (Soldering, 10s).....	+260°C
ESD Susceptibility	
HBM.....	4000V
CDM.....	1000V

### RECOMMENDED OPERATING CONDITIONS

Supply Voltage, $V_{CC}$ .....	2.0V to 5.5V
Input Voltage, $V_I$ .....	0V to 5.5V
Output Voltage, $V_O$ .....	0V to $V_{CC}$
Output Current, $I_O$ .....	$\pm 8mA$
Input Transition Rise and Fall Rate, $\Delta t/\Delta V$	
$V_{CC} = 3.3V \pm 0.3V$ .....	100ns/V (MAX)
$V_{CC} = 5.0V \pm 0.5V$ .....	20ns/V (MAX)
Operating Temperature Range.....	-40°C to +125°C

### OVERSTRESS CAUTION

- Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.
- The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.
- The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability.

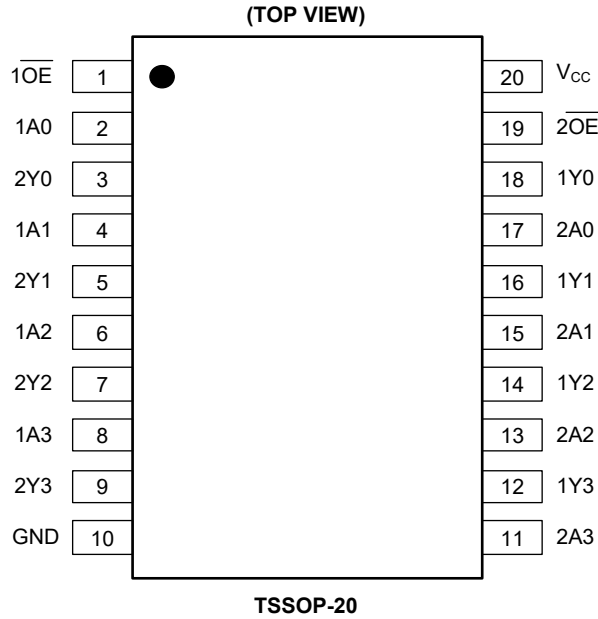
### ESD SENSITIVITY CAUTION

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

### DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

**PIN CONFIGURATION**



**PIN DESCRIPTION**

PIN	NAME	FUNCTION
1, 19	1OE, 2OE	Output Enable Inputs (Active Low).
2, 4, 6, 8	1A0, 1A1, 1A2, 1A3	Data Inputs.
18, 16, 14, 12	1Y0, 1Y1, 1Y2, 1Y3	Data Outputs.
10	GND	Ground.
17, 15, 13, 11	2A0, 2A1, 2A2, 2A3	Data Inputs.
3, 5, 7, 9	2Y0, 2Y1, 2Y2, 2Y3	Data Outputs.
20	V <sub>CC</sub>	Supply Voltage.

**ELECTRICAL CHARACTERISTICS**(Full = -40°C to +125°C, all typical values are measured at  $T_A = +25^\circ\text{C}$ , unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN	TYP	MAX	UNITS	
High-Level Input Voltage	$V_{IH}$	$V_{CC} = 2.0\text{V}$	Full	1.5			V	
		$V_{CC} = 3.0\text{V}$	Full	2.1				
		$V_{CC} = 5.5\text{V}$	Full	3.85				
Low-Level Input Voltage	$V_{IL}$	$V_{CC} = 2.0\text{V}$	Full			0.5	V	
		$V_{CC} = 3.0\text{V}$	Full			0.9		
		$V_{CC} = 5.5\text{V}$	Full			1.65		
High-Level Output Voltage	$V_{OH}$	$V_I = V_{IH}$	$I_O = -50\mu\text{A}, V_{CC} = 2.0\text{V}$	Full	1.9	1.995	V	
			$I_O = -50\mu\text{A}, V_{CC} = 3.0\text{V}$	Full	2.9	2.995		
			$I_O = -50\mu\text{A}, V_{CC} = 4.5\text{V}$	Full	4.4	4.495		
			$I_O = -4.0\text{mA}, V_{CC} = 3.0\text{V}$	Full	2.6	2.8		
			$I_O = -8.0\text{mA}, V_{CC} = 4.5\text{V}$	Full	4.0	4.25		
Low-Level Output Voltage	$V_{OL}$	$V_I = V_{IL}$	$I_O = 50\mu\text{A}, V_{CC} = 2.0\text{V}$	Full		0.005	0.1	V
			$I_O = 50\mu\text{A}, V_{CC} = 3.0\text{V}$	Full		0.005	0.1	
			$I_O = 50\mu\text{A}, V_{CC} = 4.5\text{V}$	Full		0.005	0.1	
			$I_O = 4.0\text{mA}, V_{CC} = 3.0\text{V}$	Full		0.15	0.4	
			$I_O = 8.0\text{mA}, V_{CC} = 4.5\text{V}$	Full		0.25	0.5	
Input Leakage Current	$I_I$	$V_I = 5.5\text{V}$ or GND, $V_{CC} = 0\text{V}$ to $5.5\text{V}$	Full		0.02	1	$\mu\text{A}$	
Off-State Output Current	$I_{OZ}$	$V_I = V_{IH}$ or $V_{IL}$ , $V_O = V_{CC}$ or GND, $V_{CC} = 5.5\text{V}$	Full		0.02	2	$\mu\text{A}$	
Supply Current	$I_{CC}$	$V_I = V_{CC}$ or GND, $I_O = 0\text{A}$ , $V_{CC} = 5.5\text{V}$	Full		0.02	10	$\mu\text{A}$	
Input Capacitance	$C_I$		+25°C		5.0		pF	
Output Capacitance	$C_O$		+25°C		5.0		pF	

**DYNAMIC CHARACTERISTICS**

(For test circuit, see Figure 1. Full = -40°C to +125°C, all typical values are measured at  $V_{CC} = 3.3V$  or  $5V$ ,  $T_A = +25^\circ C$ , unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN <sup>(1)</sup>	TYP	MAX <sup>(1)</sup>	UNITS	
Propagation Delay <sup>(2)</sup>	$t_{PD}$	nAn to nYn, $V_{CC} = 3.0V$ to $3.6V$	$C_L = 15pF$	Full	1.0	4.0	10.0	ns
			$C_L = 50pF$	Full	1.0	5.5	13.5	
		nAn to nYn, $V_{CC} = 4.5V$ to $5.5V$	$C_L = 15pF$	Full	1.0	3.5	6.5	
			$C_L = 50pF$	Full	1.0	4.0	8.5	
Enable Time <sup>(2)</sup>	$t_{EN}$	n $\overline{OE}$ to nYn, $V_{CC} = 3.0V$ to $3.6V$	$C_L = 15pF$	Full	1.0	6.5	12.5	ns
			$C_L = 50pF$	Full	1.0	8.0	18.0	
		n $\overline{OE}$ to nYn, $V_{CC} = 4.5V$ to $5.5V$	$C_L = 15pF$	Full	1.0	5.0	8.5	
			$C_L = 50pF$	Full	1.0	6.0	12.0	
Disable Time <sup>(2)</sup>	$t_{DIS}$	n $\overline{OE}$ to nYn, $V_{CC} = 3.0V$ to $3.6V$	$C_L = 15pF$	Full	1.0	7.0	11.0	ns
			$C_L = 50pF$	Full	1.0	11.5	16.0	
		n $\overline{OE}$ to nYn, $V_{CC} = 4.5V$ to $5.5V$	$C_L = 15pF$	Full	1.0	5.0	8.5	
			$C_L = 50pF$	Full	1.0	6.0	10.5	
Power Dissipation Capacitance <sup>(3)</sup>	$C_{PD}$	$C_L = 50pF$ , $f_i = 1MHz$ , $V_i = GND$ to $V_{CC}$	+25°C		11.0		pF	

## NOTES:

- Specified by design and characterization, not production tested.
- $t_{PD}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .  $t_{DIS}$  is the same as  $t_{PLZ}$  and  $t_{PHZ}$ .  $t_{EN}$  is the same as  $t_{PZL}$  and  $t_{PZH}$ .
- $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu W$ ).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$$

where:

$f_i$  = Input frequency in MHz.

$f_o$  = Output frequency in MHz.

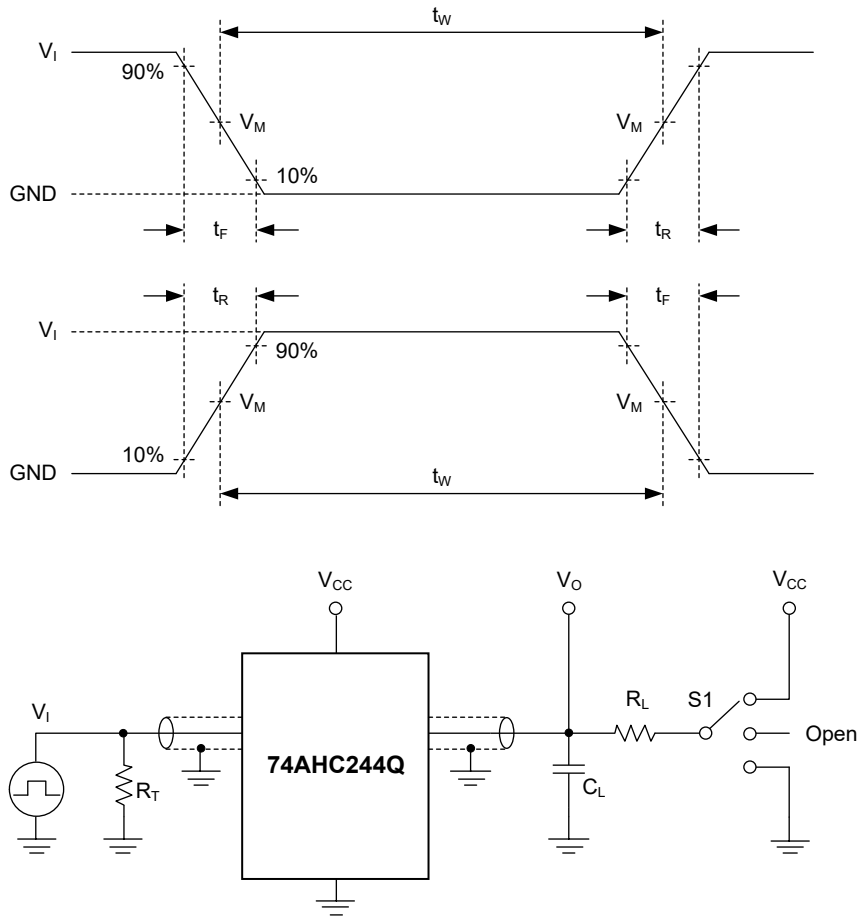
$C_L$  = Output load capacitance in pF.

$V_{CC}$  = Supply voltage in Volts.

$N$  = Number of inputs switching.

$\Sigma(C_L \times V_{CC}^2 \times f_o)$  = Sum of outputs.

TEST CIRCUIT



Test conditions are given in Table 1.

Definitions for test circuit:

$R_L$ : Load resistance.

$C_L$ : Load capacitance (includes jig and probe).

$R_T$ : Termination resistance (equals to output impedance  $Z_O$  of the pulse generator).

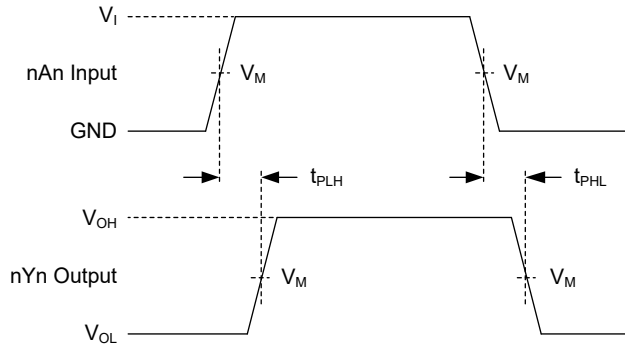
S1: Test selection switch.

Figure 1. Test Circuit for Measuring Switching Times

Table 1. Test Conditions

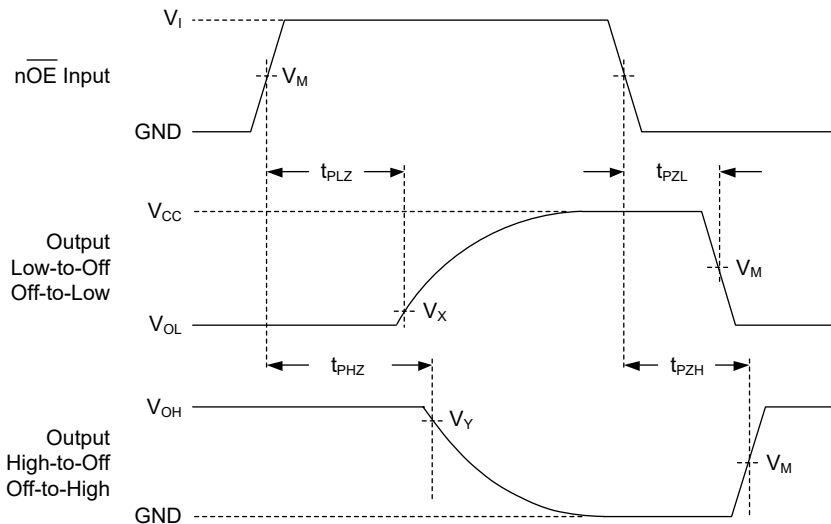
SUPPLY VOLTAGE	INPUT		LOAD		S1 POSITION		
$V_{CC}$	$V_i$	$t_R, t_F$	$C_L$	$R_L$	$t_{PHL}, t_{PLH}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
2.0V to 5.5V	$V_{CC}$	$\leq 3.0ns$	15pF, 50pF	1k $\Omega$	Open	GND	$V_{CC}$

WAVEFORMS



Test conditions are given in Table 1.  
 Measurement points are given in Table 2.  
 Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

Figure 2. Input (nAn) to Output (nYn) Propagation Delay Times



Test conditions are given in Table 1.  
 Measurement points are given in Table 2.  
 Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

Figure 3. Enable and Disable Times

Table 2. Measurement Points

SUPPLY VOLTAGE	INPUT		OUTPUT		
$V_{CC}$	$V_I$	$V_M^{(1)}$	$V_M$	$V_X$	$V_Y$
2.0V to 5.5V	$V_{CC}$	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{OL} + 0.3V$	$V_{OH} - 0.3V$

NOTE:

1. The measurement points should be  $V_{IH}$  or  $V_{IL}$  when the input rising or falling time exceeds 3.0ns.

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**REVISION HISTORY**

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

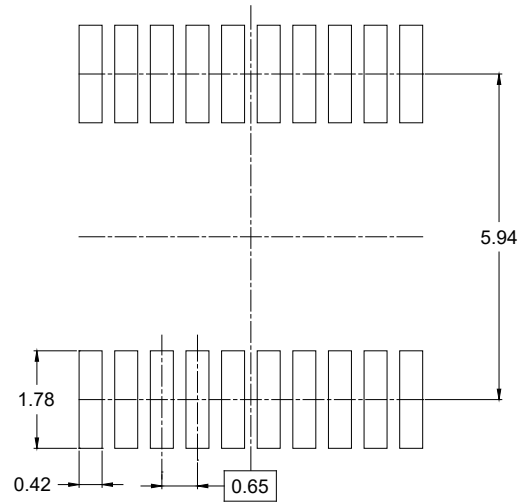
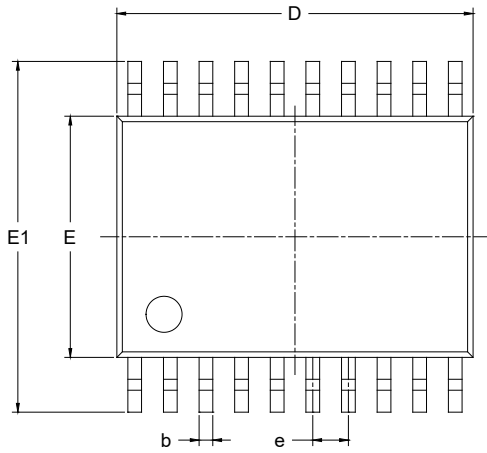
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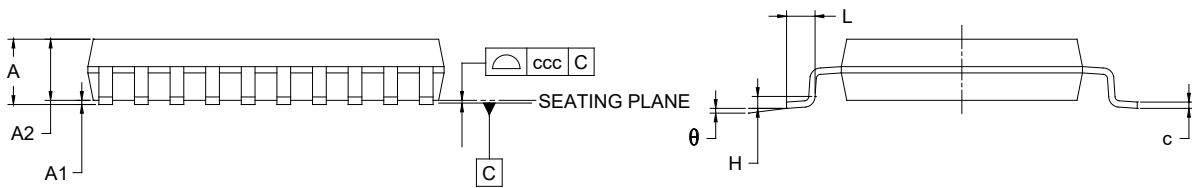


PACKAGE OUTLINE DIMENSIONS

TSSOP-20



RECOMMENDED LAND PATTERN (Unit: mm)



Symbol	Dimensions In Millimeters		
	MIN	MOD	MAX
A	-	-	1.200
A1	0.050	-	0.150
A2	0.800	-	1.050
b	0.190	-	0.300
c	0.090	-	0.200
D	6.400	-	6.600
E	4.300	-	4.500
E1	6.200	-	6.600
e	0.650 BSC		
L	0.450	-	0.750
H	0.250 TYP		
θ	0°	-	8°
ccc	0.100		

NOTES:

1. Body dimensions do not include mode flash or protrusion.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-153.

## TAPE AND REEL INFORMATION

### REEL DIMENSIONS



### TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

### KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TSSOP-20	13"	16.4	6.80	6.90	1.50	4.0	8.0	2.0	16.0	Q1

DD0001

# PACKAGE INFORMATION

## CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

## KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
13"	386	280	370	5

DD0002